

DESCRIPTION

The AO3407A is the high cell density trenched P-ch MOSFETs, which provides excellent RDSON and efficiency for most of the small power switching and load switch applications.

The AO3407A meet the RoHS and Green Product requirement with full function reliability approved.

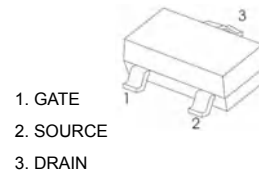
FEATURES

Green Device Available
Super Low Gate Charge
Excellent CdV/dt effect decline
Advanced high cell density Trench technology

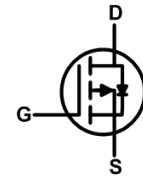
V_{DS} -30 V
 I_D -4.2 A
 $R_{DS(ON)}$ 41 m Ω

3407

SOT-23



Equivalent Circuit



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|----------------------------|--------------------------------------|------------|------------------|
| V_{DS} | Drain-Source Voltage | -30 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| $I_D@T_A=25^\circ\text{C}$ | Continuous Drain Current | -4.2 | A |
| $I_D@T_A=70^\circ\text{C}$ | Continuous Drain Current | -3.6 | A |
| I_{DM} | Pulsed Drain Current ² | -16 | A |
| $P_D@T_A=25^\circ\text{C}$ | Total Power Dissipation ³ | 1.5 | W |
| $P_D@T_A=70^\circ\text{C}$ | Total Power Dissipation ³ | 1.0 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ\text{C}$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ\text{C}$ |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|--------------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ¹ | --- | 105 | $^\circ\text{C/W}$ |
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ¹ (t ≤ 10 s) | --- | --- | $^\circ\text{C/W}$ |

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|--|---------------|--|------|------|-----------|------------|
| Static Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS}=0V, I_D=-250\mu A$ | -30 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=-30V, V_{GS}=0V$ | - | - | -1 | μA |
| Gate-Source Leakage | I_{GSS} | $V_{DS}=0V, V_{GS}=\pm 20V$ | - | - | ± 100 | nA |
| Gate-Source Threshold voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=-250\mu A$ | -1 | -1.5 | -2.5 | V |
| Drain-Source on-State Resistance ³ | $R_{DS(on)}$ | $V_{GS}=-10V, I_D=-4.1A$ | - | 41 | 60 | m Ω |
| | | $V_{GS}=-4.5V, I_D=-3A$ | - | 53 | 85 | |
| Dynamic Characteristics⁴ | | | | | | |
| Input Capacitance | C_{iss} | $V_{GS}=0V, V_{DS}=-15V,$ $f=1.0MHz$ | - | 530 | - | pF |
| Output Capacitance | C_{oss} | | - | 70 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 56 | - | |
| Switching Characteristics⁴ | | | | | | |
| Total Gate Charge | Q_g | $V_{GS}=-10V, V_{DS}=-15V,$ $I_D=-4.1A$ | - | 6.8 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 1.0 | - | |
| Gate-Drain Charge | Q_{gd} | | - | 1.4 | - | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{GS}=-10V, V_{DS}=-15V,$ $R_L=15\Omega, R_{GEN}=2.5\Omega$ | - | 14 | - | ns |
| Rise Time | t_r | | - | 61 | - | |
| Turn-off Delay time | $t_{d(off)}$ | | - | 19 | - | |
| Fall Time | t_f | | - | 10 | - | |
| Source-Drain Body Diode Characteristics | | | | | | |
| Diode Forward Voltage ³ | V_{SD} | $I_S=-4.1A, V_{GS}=0V$ | - | - | -1.2 | V |
| Continuous Source Current | I_S | | - | - | -4.5 | A |

Notes:

1. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^\circ\text{C}$.
2. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
3. Pulse Test: Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. This value is guaranteed by design hence it is not included in the production test.

RATING AND CHARACTERISTIC CURVES

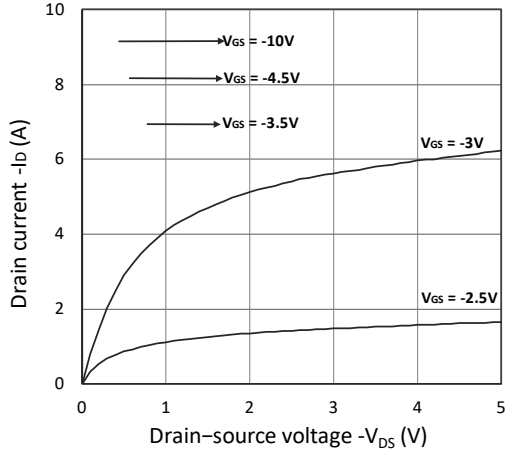


Figure 1. Output Characteristics

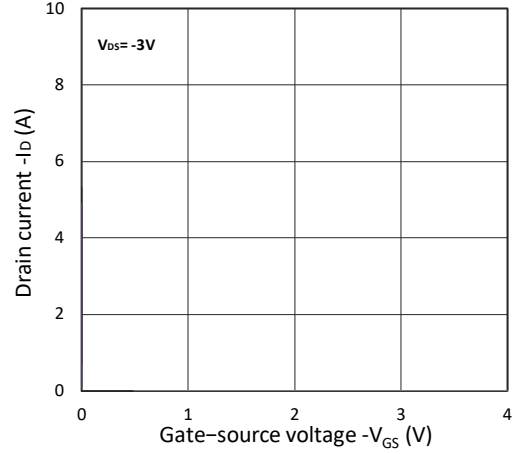


Figure 2. Transfer Characteristics

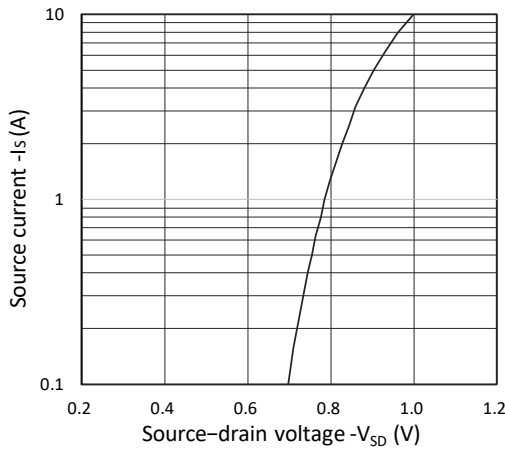


Figure 3. Forward Characteristics of Reverse

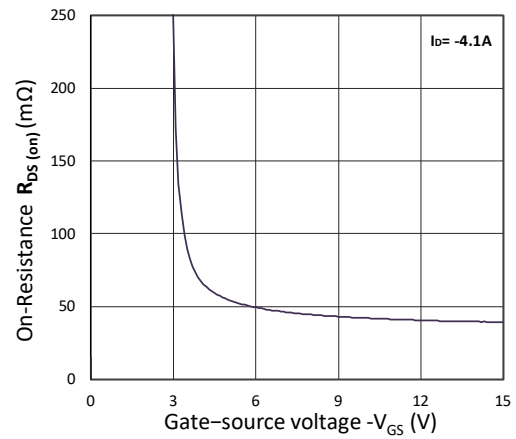


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

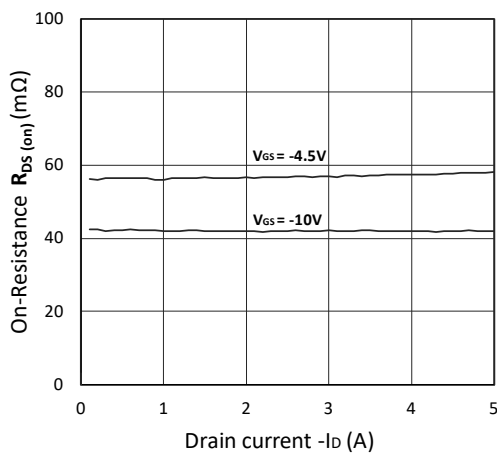


Figure 5. $R_{DS(ON)}$ vs. I_D

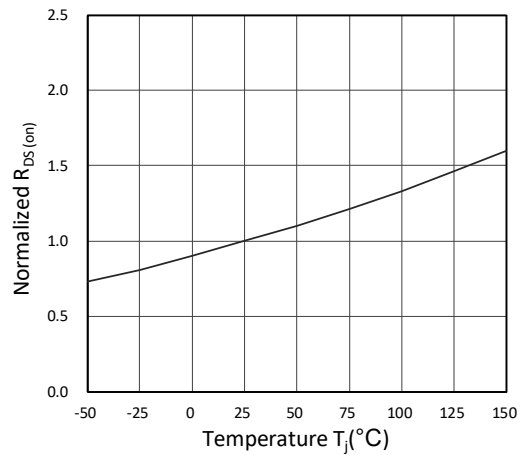


Figure 6. Normalized $R_{DS(ON)}$ vs. Temperature

RATING AND CHARACTERISTIC CURVES

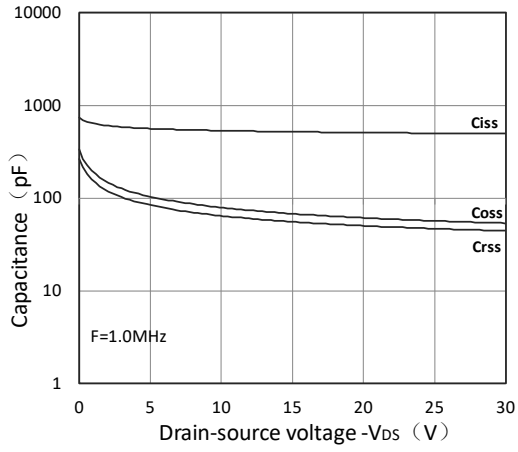


Figure 7. Capacitance Characteristics

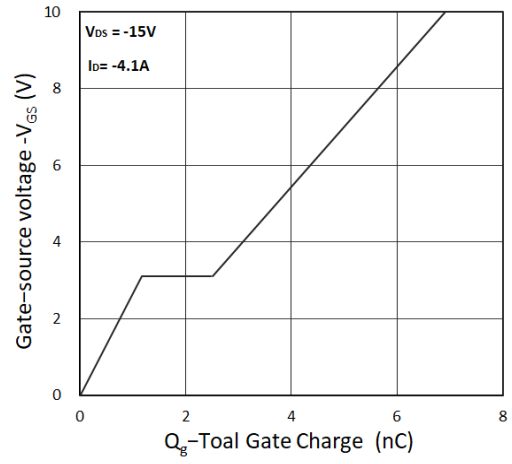
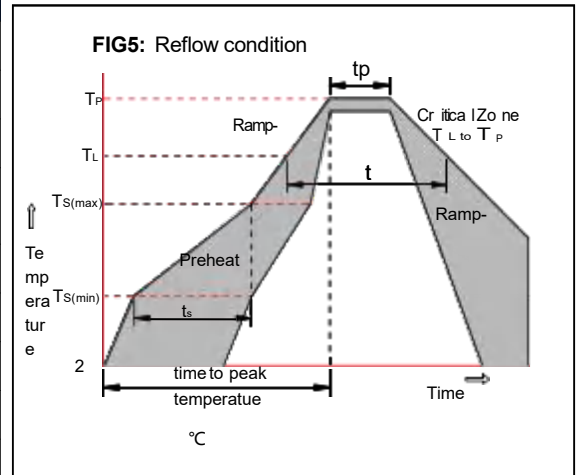


Figure 8. Gate Charge Characteristics

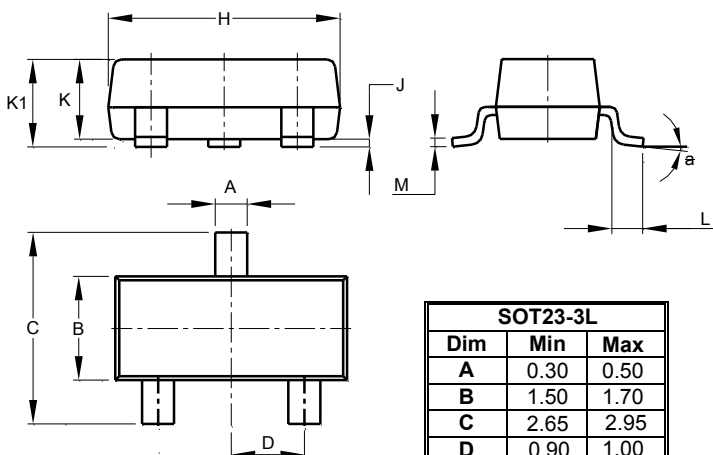
Soldering parameters

| Reflow Condition | | Pb-Free assembly (see as below) |
|---|-----------------------------------|------------------------------------|
| Pre Heat | -Temperature Min ($T_{s(min)}$) | +150°C |
| | -Temperature Max($T_{s(max)}$) | +200°C |
| | -Time (Min to Max) (ts) | 60-180 secs. |
| Average ramp up rate (Liquid us Temp (T_L) to peak) | | 3°C/sec. Max |
| $T_{s(max)}$ to T_L - Ramp-up Rate | | 3°C/sec. Max |
| Reflow | -Temperature(T_L)(Liquid us) | +217°C |
| | -Temperature(t_L) | 60-150 secs. |
| Peak Temp (T_P) | | +260(+0/-5)°C |
| Time within 5°C of actual Peak Temp (t_p) | | 30 secs. Max |
| Ramp-down Rate | | 6°C/sec. Max |
| Time 25°C to Peak Temp (T_P) | | 8 min. Max |
| Do not exceed | | +260°C |

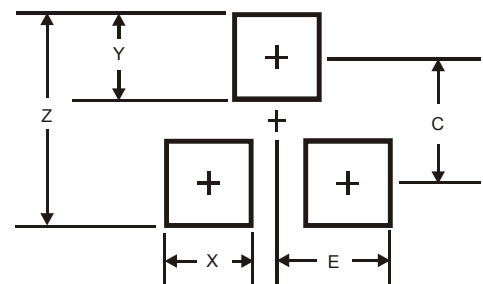


Package Dimensions & Suggested Pad Layout

SOT23-3L



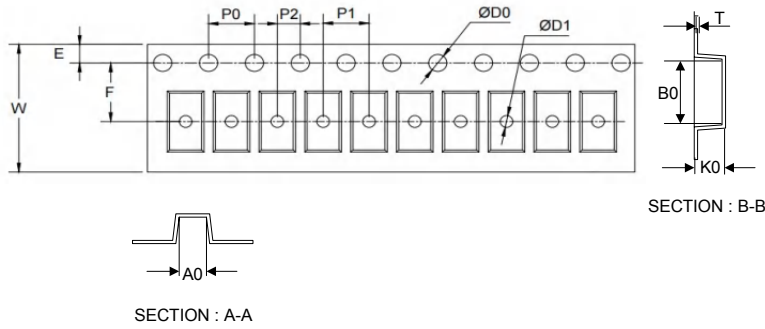
| SOT23-3L | | |
|----------------------|------|------|
| Dim | Min | Max |
| A | 0.30 | 0.50 |
| B | 1.50 | 1.70 |
| C | 2.65 | 2.95 |
| D | 0.90 | 1.00 |
| H | 2.82 | 3.02 |
| J | | 0.10 |
| K | 1.05 | 1.15 |
| K1 | 1.05 | 1.25 |
| L | 0.30 | 0.60 |
| M | 0.10 | 0.20 |
| a | 0° | 8° |
| All Dimensions in mm | | |



| Dimensions | SOT23-3L |
|------------|----------|
| Z | 3.3 |
| X | 0.9 |
| Y | 1.0 |
| C | 2.3 |
| E | 1.40 |

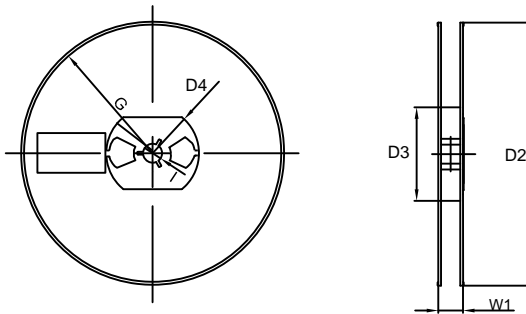
Tape & reel specification

Tape



| Symbol | Dimension (mm) |
|--------|----------------|
| P0 | 4.00±0.20 |
| P1 | 4.00±0.20 |
| P2 | 2.00±0.20 |
| D0 | 1.55±0.20 |
| D1 | 1.05±0.20 |
| E | 1.55±0.20 |
| F | 3.60±0.20 |
| W | 8.00±0.20 |
| A0 | 3.80±0.20 |
| B0 | 3.50±0.20 |
| K0 | 1.55±0.20 |
| T | 0.25±0.15 |
| D2 | 178.0±5.0 |
| D3 | 55Min. |
| D4 | R24.0±3.0 |
| G | R82.0±3.0 |
| I | 13.0±2.0 |
| W1 | 11.0±3.0 |

7" Reel



Quantity: 3000PCS